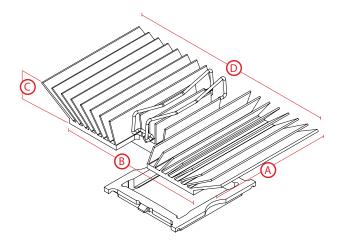


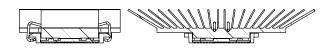
Custom High Performance Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-59006-C2-R0

Features & Benefits

- » Designed for flip-chip processors such as Freescale MPCs
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Comes preassembled with high performance, phase changing, thermal interface material





Thermal Performance

*Image above is for illustration purposes only.

| AIR VELOCITY | | THERMAL RESISTANCE | | |
|--------------|-----|----------------------|--------------------|--|
| FT/MIN | M/S | °C/W (UNDUCTED FLOW) | °C/W (DUCTED FLOW) | |
| 200 | 1.0 | 6.2 | 3.8 | |
| 300 | 1.5 | 4.9 | | |
| 400 | 2.0 | 4.2 | | |
| 500 | 2.5 | 3.7 | | |
| 600 | 3.0 | 3.3 | | |
| 700 | 3.5 | 3 | | |
| 800 | 4.0 | 2.8 | | |

Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH |
|-------------|-------------|-------------|-------------|---------------------|----------------|
| 29 mm | 37 mm | 11 mm | 54 mm | SAINT-GOBAIN C1100F | BLACK-ANODIZED |

NOTES

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- ATS-59006-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).